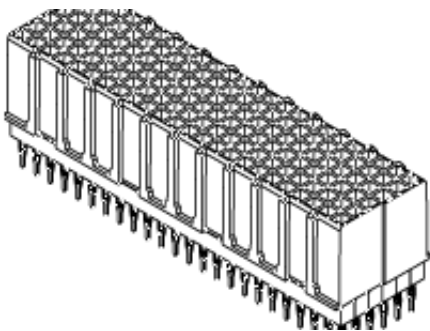




Part Number : [737801255](#)
Product Description : HDM Board-to-Board
Daughtercard Receptacle, Vertical, Signal
Module, 144 Circuits, Mounted Height
15.00mm, Pin Length 3.50mm, Solder Tail
Series Number : 73780
Status : Active
Product Category : Backplane Connectors



Documents & Resources

Drawings
[Drawing 737801255_sd.pdf](#)

3D Models and Design Files
[3D Model 737801255_stp.zip](#)

Specifications
[Application Specification AS-73670-9998-001.pdf](#)
[Product Specification PS-73780-999-001.pdf](#)

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2022)9120-DC (17 Jan 2023)
EU RoHS	Compliant per EU 2015/863

- Multiple Part Product Compliance Statements
- Eu RoHS
 - REACH SVHC
 - Low-Halogen

- Multiple Part Industry Compliance Documents
- IPC 1752A Class C
 - IPC 1752A Class D

- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	Backplane Connectors
Series	73780
Description	HDM Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 15.00mm, Pin Length 3.50mm, Solder Tail
Application	Daughtercard, Mezzanine
Comments	Solder Tail
Component Type	PCB Receptacle
Product Family	HDM Backplane Connector System
Product Name	HDM
UPC	822348038732

Agency

UL	E29179
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Electrical

Current - Maximum per Contact	15.0A, 1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black

Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	15.334/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
Packaging Type	Tube
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.60mm
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762μm
Plating min - Termination	2.540μm
Polarized to PCB	No
Stackable	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface Style	Through Hole

Solder Process Data

Max-Duration	5
Lead-Free Process Capability	WAVE
Max-Cycle	1
Max-Temp	260

Mates With / Use With

Mates with Part(s)

Description	Part Number
HDM Vertical Backplane Headers	<u>73642</u>
HDM Vertical Backplane Headers	<u>73643</u>
HDM Vertical Backplane Headers	<u>73644</u>
HDM Vertical Backplane Headers	<u>73942</u>
HDM Vertical Backplane Headers	<u>73944</u>
HDM Vertical Stacking Headers	<u>73769</u>
HDM Vertical Stacking Headers	<u>73782</u>
HDM Vertical Stacking Headers	<u>73771</u>